Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-18. (canceled)

19. (currently amended) An article of manufacture comprising:

a machine-accessible medium including data that, when accessed by a machine, causes the machine to:

~~a machine-accessible medium including data that, when accessed by a machine, causes the machine to:~~

control an imaging sensor to obtain a scribe pattern on a front side of a wafer placed on a chuck, the front side being attached to a tape;

recognize the scribe pattern; and

control a laser to mark an alignment pattern on a back side of the wafer based on the scribe pattern, the laser being mounted above the chuck.

20. (original) The article of manufacture of claim 19 wherein the data causing the machine to control the imaging sensor comprises data that, when accessed by the machine, causes the machine to:

control the imaging sensor mounted above the wafer.

21. (original) The article of manufacture of claim 19 wherein the data causing the machine to control the imaging sensor comprises data that, when accessed by the machine, causes the machine to:

control the imaging sensor mounted underneath the wafer.

22. (original) The article of manufacture of claim 19 wherein the data causing the machine to control the laser comprises data that, when accessed by the machine, causes the machine to:

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emit a laser beam from the laser to etch the alignment pattern on the back side, the alignment pattern being directly opposite to the scribe pattern.

23. (original) The article of manufacture of claim 19 wherein the data further comprises data that, when accessed by the machine, causes the machine to:

activate a flipping mechanism to turn the back side of the wafer up.

24. (original) The article of manufacture of claim 19 wherein the data further comprises data that, when accessed by the machine, causes the machine to:

save the scribe pattern in a memory.

25. (original) The article of manufacture of claim 19 wherein the data further comprises data that, when accessed by the machine, causes the machine to:

recognize the alignment pattern on the back side of the wafer.

26. (original) The article of manufacture of claim 25 wherein the data further comprises data that, when accessed by the machine, causes the machine to:

control a cutting mechanism to cut the back side of the wafer based on the alignment pattern.

27-36. (canceled)

37. (previously presented) A method comprising:

controlling an imaging sensor to obtain a scribe pattern on a front side of a wafer placed on a chuck, the front side being attached a tape;

recognizing the scribe pattern; and

controlling a laser to mark an alignment pattern on a back side of the wafer based on the scribe pattern, the laser being mounted above the chuck.

38. (previously presented) The method of claim 37 wherein controlling the imaging sensor comprises:

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controlling the imaging sensor mounted above the wafer.

39. (previously presented) The method of claim 37 wherein controlling the imaging sensor comprises:

controlling the imaging sensor mounted underneath the wafer.

40. (previously presented) The method of claim 37 wherein controlling the laser comprises:

emitting a laser beam from the laser to etch the alignment pattern on the back side, the alignment pattern being directly opposite to the scribe pattern.

41. (previously presented) The method of claim 37 wherein further comprising:

activating a flipping mechanism to turn the back side of the wafer up.

42. (previously presented) The method of claim 37 further comprising:

saving the scribe pattern in a memory.

43. (previously presented) The method of claim 37 further comprising:

recognizing the alignment pattern on the back side of the wafer.

44. (previously presented) The method of claim 43 wherein further comprising:

controlling a cutting mechanism to cut the back side of the wafer based on the alignment pattern.

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